

ABSTRACT OF THE DISCLOSURE

Disclosed are an image sensor module of a camera and an assembling method thereof capable of simultaneously bonding a circuit pattern and an infrared ray filter to an upper surface of a circuit board section. The image sensor module has the circuit board

5 section including a bonding part made of transparent material. The circuit board section has an upper surface onto which the circuit pattern and the infrared ray filter are simultaneously bonded. An image sensor chip is bonded to a lower surface of the circuit board section using a flip chip bonding technique. A lens holder is bonded to the upper surface of the circuit board section using an epoxy bonding process. A lens assembly is

10 bonded to an upper surface of the lens holder using the epoxy bonding process.